

DESCRIPTION

R8A66173 has four 12-bit PWM (Pulse Width Modulation) circuits which are built by using the CMOS process.

This IC controls PWM waveform by adjusting the "H" width according to serial data sent from MCU (Micro Controller Unit) or other device. Each channel can be independently controlled.

High-resolution digital-analog (D-A) converter can be formed easily by connecting a low-pass filter (LPF) circuit to the output pins of this circuit.

R8A66173 is the succession product of M66242.

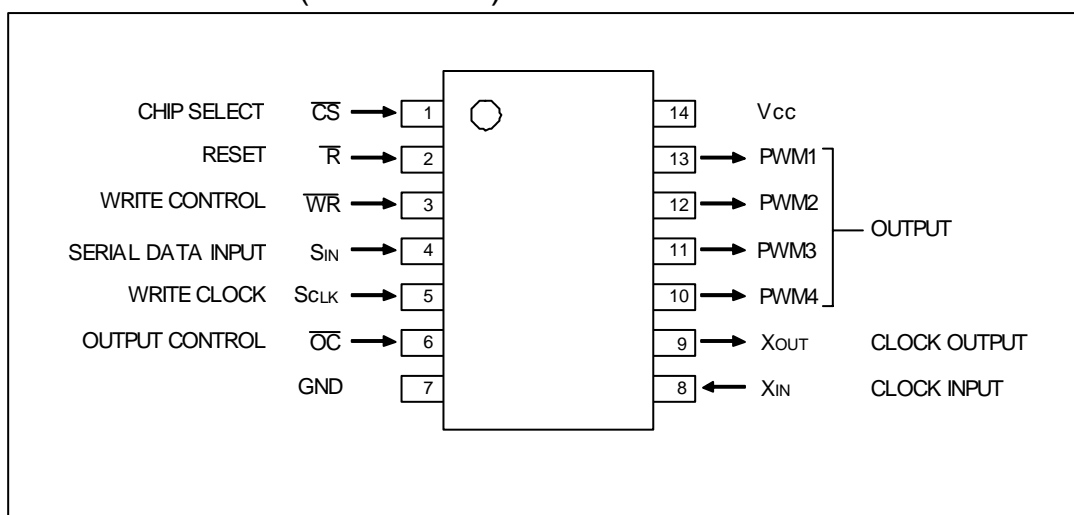
FEATURES

- Built-in four 12-bit high-resolution PWM circuits
- Easy D-A conversion – Quick output waveform smoothing
Control by 1.22mV possible per step (Vcc=5V range)
- Serial data input
- "H" level width setting type
- 4 channels controlled independently
- All 4 channels reset by reset input (\overline{R}), High-impedance status after reset
- All 4 channels controlled by output control input (\overline{OC})
- Settings take effect after ongoing cycle is completed
- Output : CMOS 3-state output
Output current $I_o = \pm 4\text{mA}$ (Vcc=5.0V range), $I_o = \pm 2\text{mA}$ (Vcc=3.3V range)
- Wide operating supply voltage range (Vcc=3.0~3.6V or Vcc=4.5~5.5V, single power supply)
- Wide operating temperature range: Ta=-40°C~+85°C

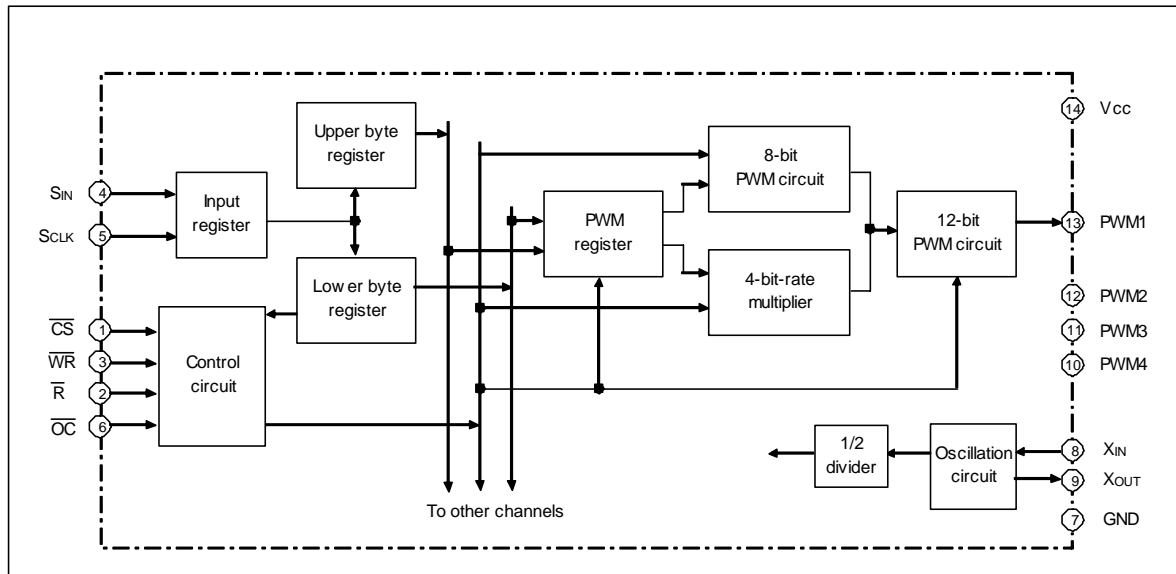
APPLICATION

- Analog signal control in televisions and audio systems
- Control of lamps, heaters and motors
- For software servo in home appliances and industrial machinery

PIN CONFIGURATION (TOP VIEW)



BLOCK DIAGRAM (EACH CHANNEL)



FUNCTION

The PWM output waveform of each channel is controlled by taking in PWM data from MCU or other device via serial data input SIN.

12-bit PWM data is input being divided between upper 8-bits (upper byte) and lower 4-bits.

The lower 4-bit data is combined with command data such as channel designation and input as 8-bit data (lower byte).

The lower byte should be written first, and then the upper byte. Even if only the upper byte is to be changed, rewrite from the lower byte.

The PWM waveform changes according to the new setting from the next cycle.

One cycle of PWM waveform (=4096 divisions; 12-bit resolution) are divided into 16 (2^4) subsections t . Each subsection consists of 256 ($=2^8$; 8-bit resolution) minimum bits $\tau (=2/f_{XIN}^{**})$.

One subsection t consists of an 8-bit PWM waveform (basic waveform). The "H" width of this waveform is determined according to the upper 8-bits of PWM data. One cycle has 16 subsections t , each of which has this basic waveform. Among them, those which are designated by the 4-bit-rate multiplier are conditioned to have a "H" width that is longer by τ . The lower 4-bits of PWM data are used to specify those subsections (tm). The waveform of other subsections remains unchanged.

The PWM waveform (12-bit resolution) is a combination of two types of waveforms which are different in "H" width, as described above.

When output control input \overline{OC} is "H", the output of every 4-channel turns high-impedance from the next cycle.

When reset input \overline{R} is "L", the output of every channel turns high-impedance as soon as the ongoing cycle is completed, and PWM data of all channels is reset. If \overline{R} input is changed from "L" to "H", the next cycle starts, however, the output of the channels remains high-impedance.

To enable output, rewrite input data for each channel.

** f_{XIN} : Clock XIN repeat frequency

PIN DESCRIPTIONS

Pin	Name	Input/Output	Functions
\overline{R}	Reset input	Input	"L" : All 4-channels put in high-impedance state.
\overline{CS}	Chip select input	Input	"L" : Communication with MCU becomes possible. \overline{WR} , SIN and $SCLK$ put in enable state.
\overline{WR}	Write control input	Input	"L": Serial data written. "L"-to-"H" edge: Written data stored in upper or lower byte register.
SIN	Serial data input	Input	Inputs 8-bit serial data from MCU synchronously with $SCLK$ clock.
$SCLK$	Write clock input	Input	Inputs sync clock pulses for 8-bit serial data writing.
\overline{OC}	Output control input	Input	"H": All 4-channels put in high-impedance state.
PWM1 ~ PWM4	PWM outputs 1 ~ 4	Output	Outputs PWM waveform. (CMOS 3-state output)
XIN	Clock input	Input	Input/output signals generated by clock signal generation circuit. Oscillation frequency is determined by connecting ceramic or quartz resonator between XIN and $XOUT$. The frequency of internal clock (PWM timing clock) signals is the 1/2 divider of the frequency input from clock input XIN .
$XOUT$	Clock output	Output	When external clock signals are used, connect clock generator to XIN pin and leave $XOUT$ open.

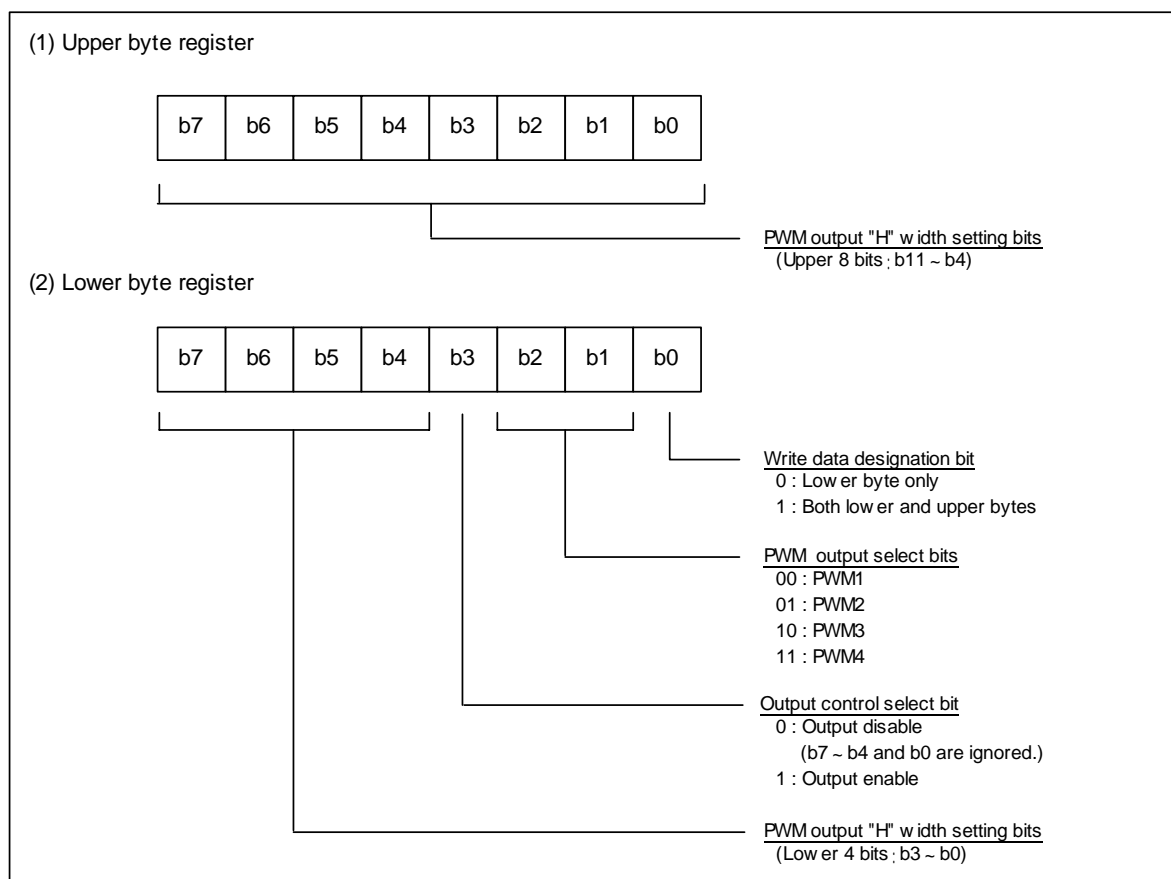


Fig. 1 Upper and Lower Byte Register Makeup

Table 1 Mode Selection

Mode		Input serial data															
		Lower byte data								Upper byte data							
PWM data setting (output enable)	Lower 4-bit data setting	b7	b6	b5	b4	1	b2	b1	0	-							
	12-bit data setting	b7	b6	b5	b4	1	b2	b1	1	b7	b6	b5	b4	b3	b2	b1	b0
Output disable		X	X	X	X	0	b2	b1	X	-							

Table 2 Patterns of Lower 4-bits and Subsections whose "H" Width is increased

PWM register b3 ~ b0	Subsection tm whose H width is increased by (m = 0 ~ 15)	Number of Subsections
0000	Nothing	0
0001	m = 8	1
0010	m = 4, 12	2
0100	m = 2, 6, 10, 14	4
1000	m = 1, 3, 5, 7, 9, 11, 13, 15	8
1111	m = 1 ~ 15 (m = 0)	15

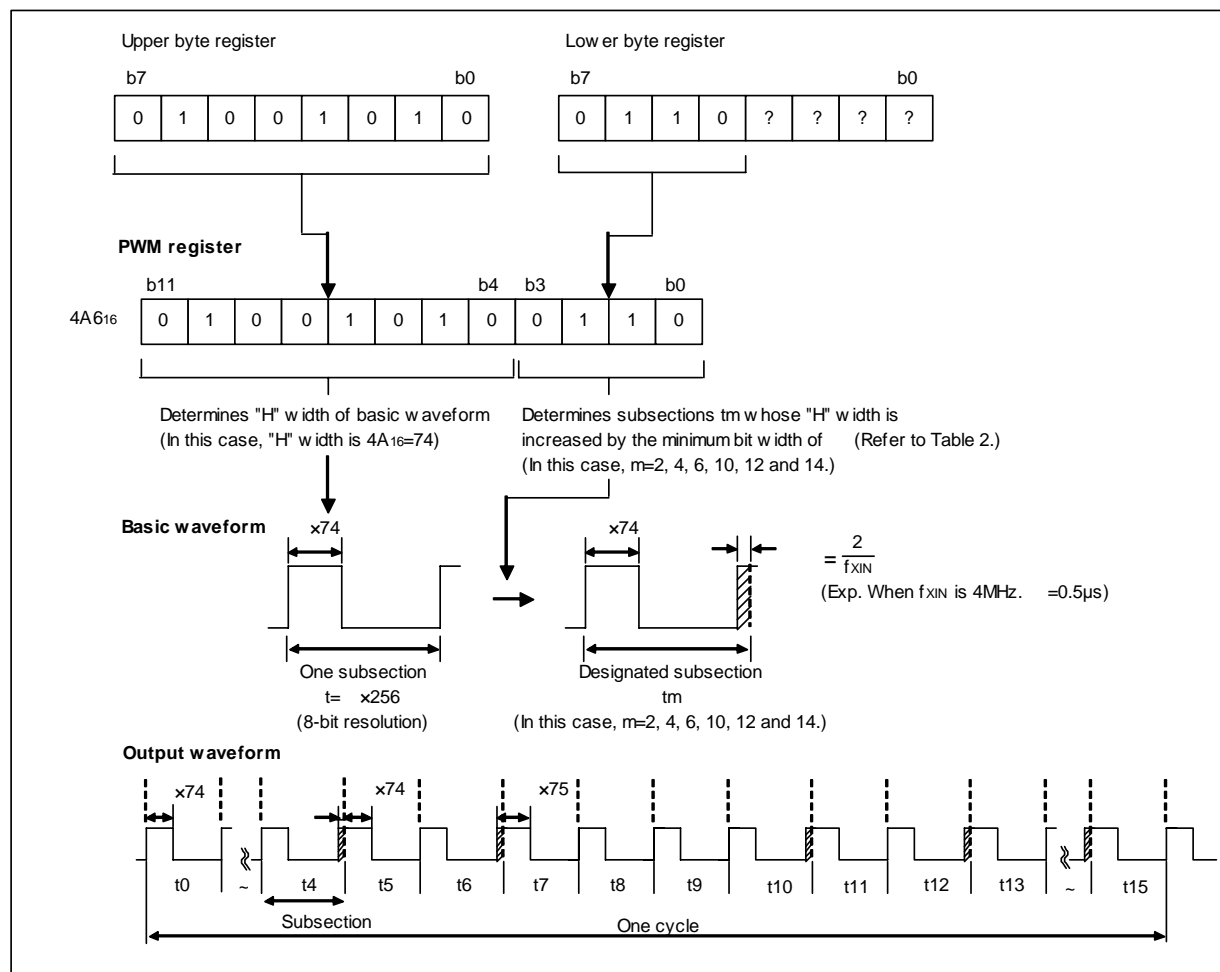


Fig.2 PWM Waveform Output Example (Input data:4A616)

OPERATION

Serial Data Input

When chip select \overline{CS} is "L" and write control input \overline{WR} is "L", data input to SIN at the edge where write clock input $SCLK$ status shifts from "L" to "H" is written. (See Fig.3.) At the edge where \overline{WR} rises from "L" to "H", the latest 8-bit data writing is completed, and input data is stored in lower (or upper) byte register. When writing on the lower byte or writing on both upper and lower bytes is completed, data on the lower byte register or, in the latter case, data on both lower and upper byte registers is written on the PWM register of the channel designated by lower bytes b2 and b1. All setting process ends with this writing, and PWM waveform changes according to the setting from the next cycle.

PWM Waveform Output

(1) 12-bit PWM output

One PWM waveform cycle is divided into $16(=2^4)$ subsections t , and each subsection is further divided into $256(=2^8)$ minimum resolution bits $\tau(=2/f_{XIN})$. The "H" width of subsection t basic waveform is determined by the upper 8-bits of PWM data. (In Fig.2 above, "H" width is $4A_{16}=74\times\tau$)

Among these 16 subsections t , subsections t_m designated by the lower 4-bits of PWM data have "H" width that is longer by τ .

(In Fig.2 above, the "H" width of designated 6 subsections ($m=2, 4, 6, 10, 12$ and 14) is $4B_{16}=75\times\tau$.)

The "H" width of undesignated subsections remains unchanged.

As explained above, one cycle of waveform is a combination of two waveforms different in the "H" width.

(In Fig. 2 above, one cycle consists of 10 subsections whose "H" width is $74\times\tau$ and 6 subsections whose "H" width is $75\times\tau$)

Note: It is impossible to set one whole cycle to "H" level.

(2) 8-bit PWM output

As can be seen from the 12-bit PWM waveform output process as described above, 8-bit resolution PWM waveform can be output by fixing the lower 4-bits of PWM data to 0000.

All subsections from t_0 to t_{15} have the "H" width as determined by the upper 8-bits of PWM data.

Note: It is impossible to set one whole cycle to "H" level.

Output Control

(1) Serial data input

By using data on lower byte register b3 (output control selection bit), output of each channel can be controlled independently. The state of the selected PWM output changes after the completion of the ongoing cycle.

When b3 is set 0, lower byte register b0 (write data designation bit) is reset. Do not write on upper byte in this case.

(2) Output control input

The status of all 4-channel outputs during a cycle is determined depending on the status of output control input OC at the start of the cycle. (See Fig. 6.)

Even when output is in a high-impedance state, data on each PWM register is retained, and data can be rewritten.

(3) Reset

When reset input \overline{R} turns "L", all operation is reset as soon as the ongoing cycle is completed. The outputs of all 4-channels turn high-impedance. The PWM register of each channel is reset.

When \overline{R} is shifted from "L" to "H", a next cycle starts, and data writing becomes possible. However, outputs stay in the high-impedance state. (See Fig. 6)

To resume output, write input data for each channel.

Initial State

After power-on, outputs and PWM register data are unstable.

(1) Reset

Reset input \overline{R} is kept on "L" level for more than one cycle (2.048ms when f_{XIN} is 4 MHz) or more, this integrated circuit is put in a reset state.

If stabilization needs more time, e.g. when a quartz resonator is used, keep \overline{R} on "L" level for an adequate period of time.

(2) Serial data input

When starting using this integrated circuit without resetting, input false lower byte data ($b_0=0$) to stabilize lower byte register b0 data, and then input normal data.

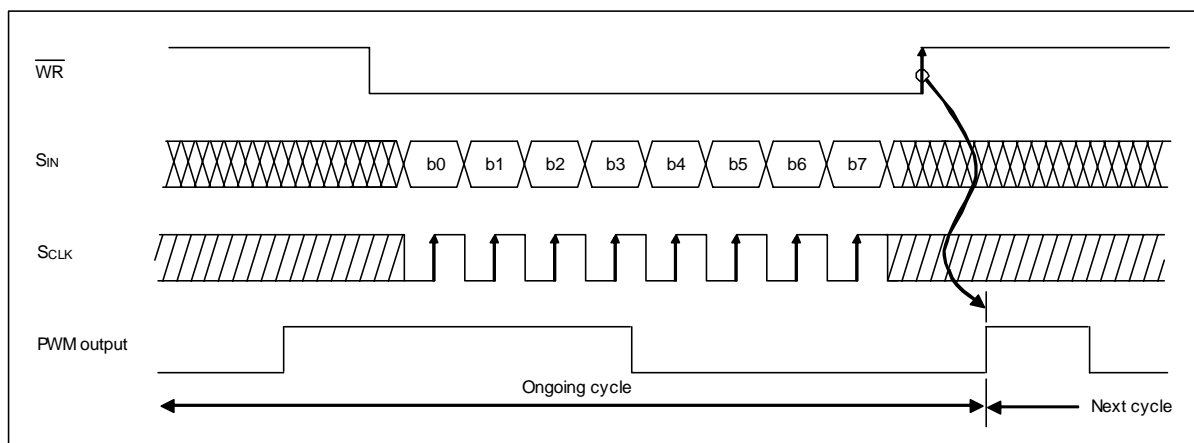


Fig.3 Serial Data Write Timing

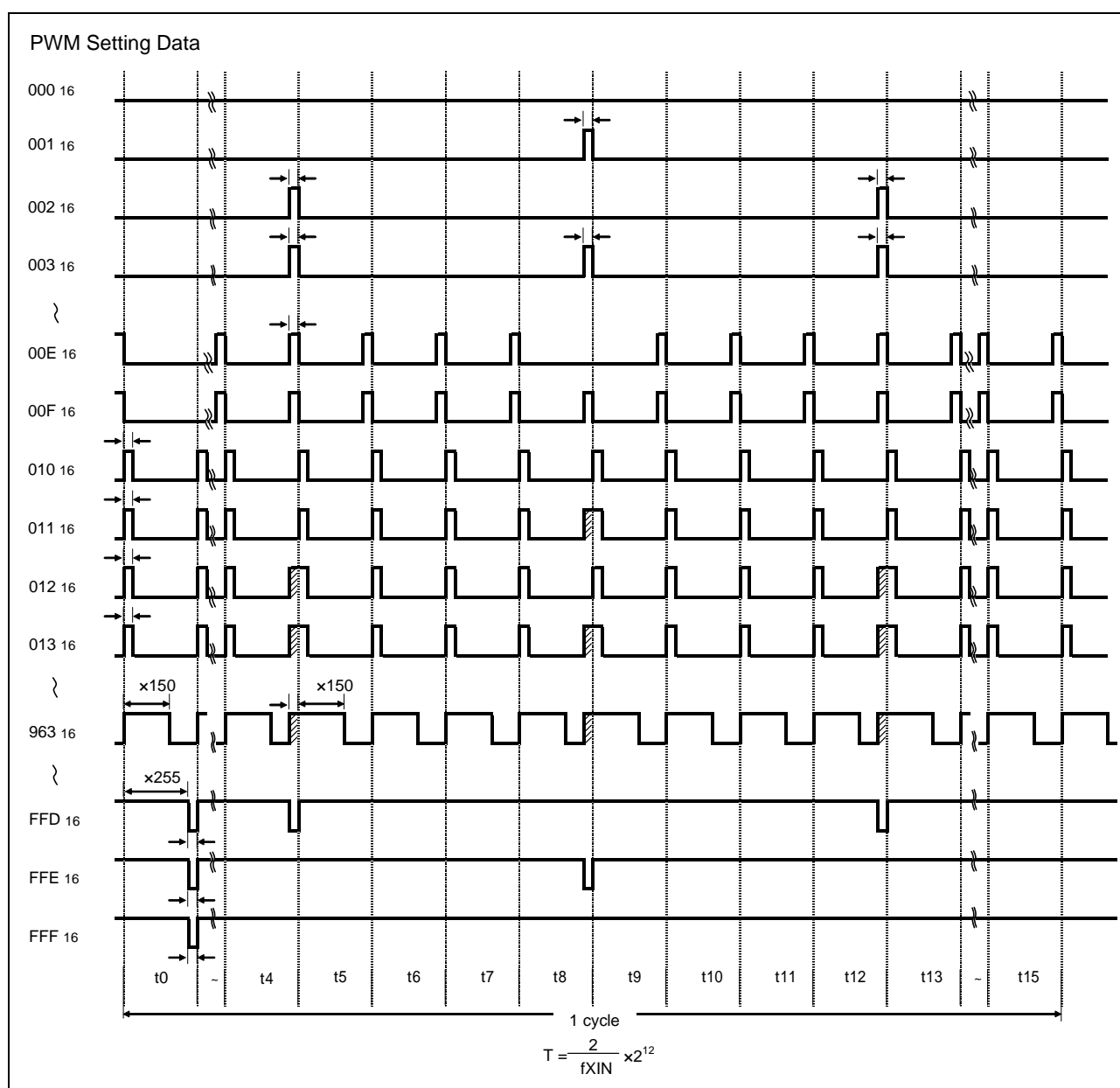


Fig.4 12-bit PWM Waveform Output Example

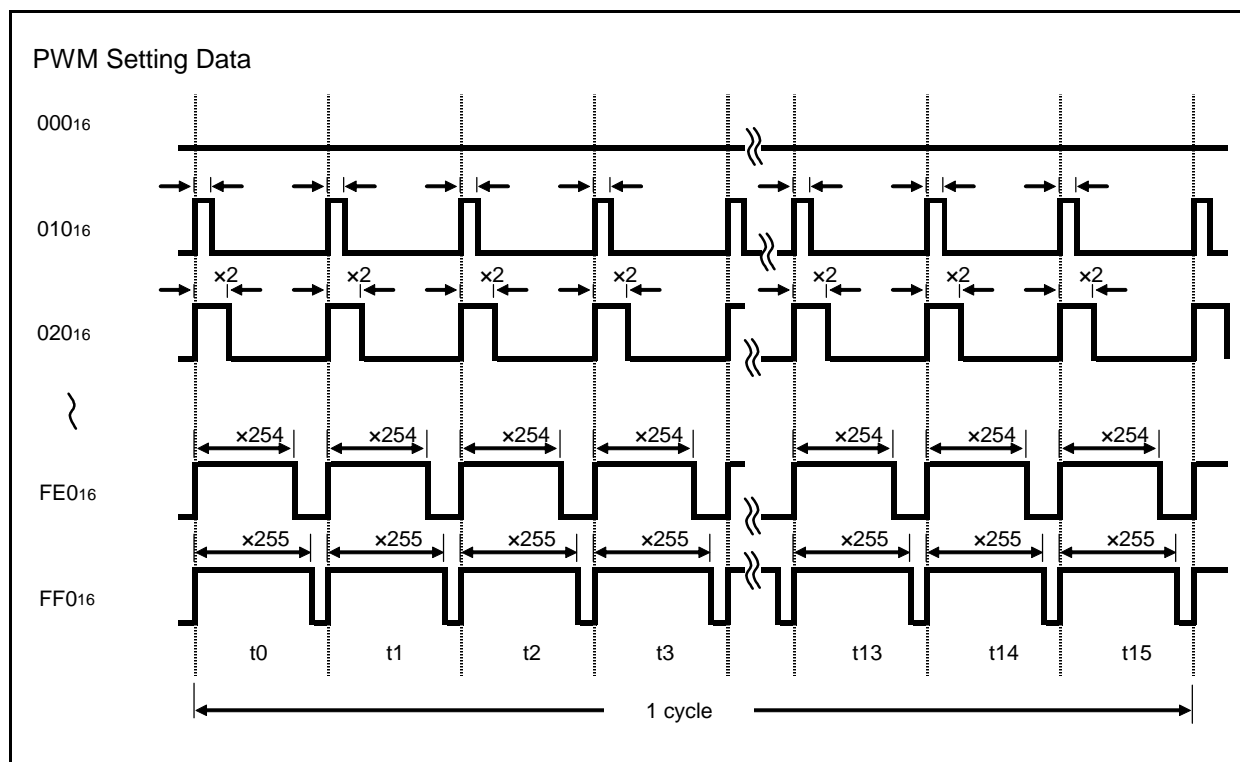


Fig.5 8-bit PWM Waveform Output Example

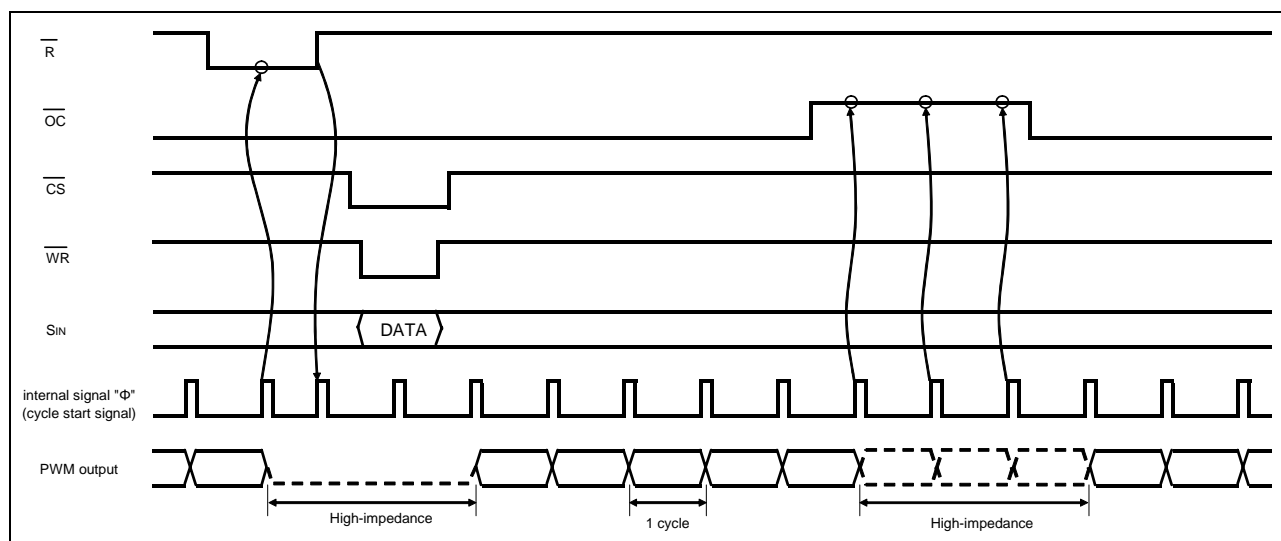


Fig.6 Output Control Timing Chart

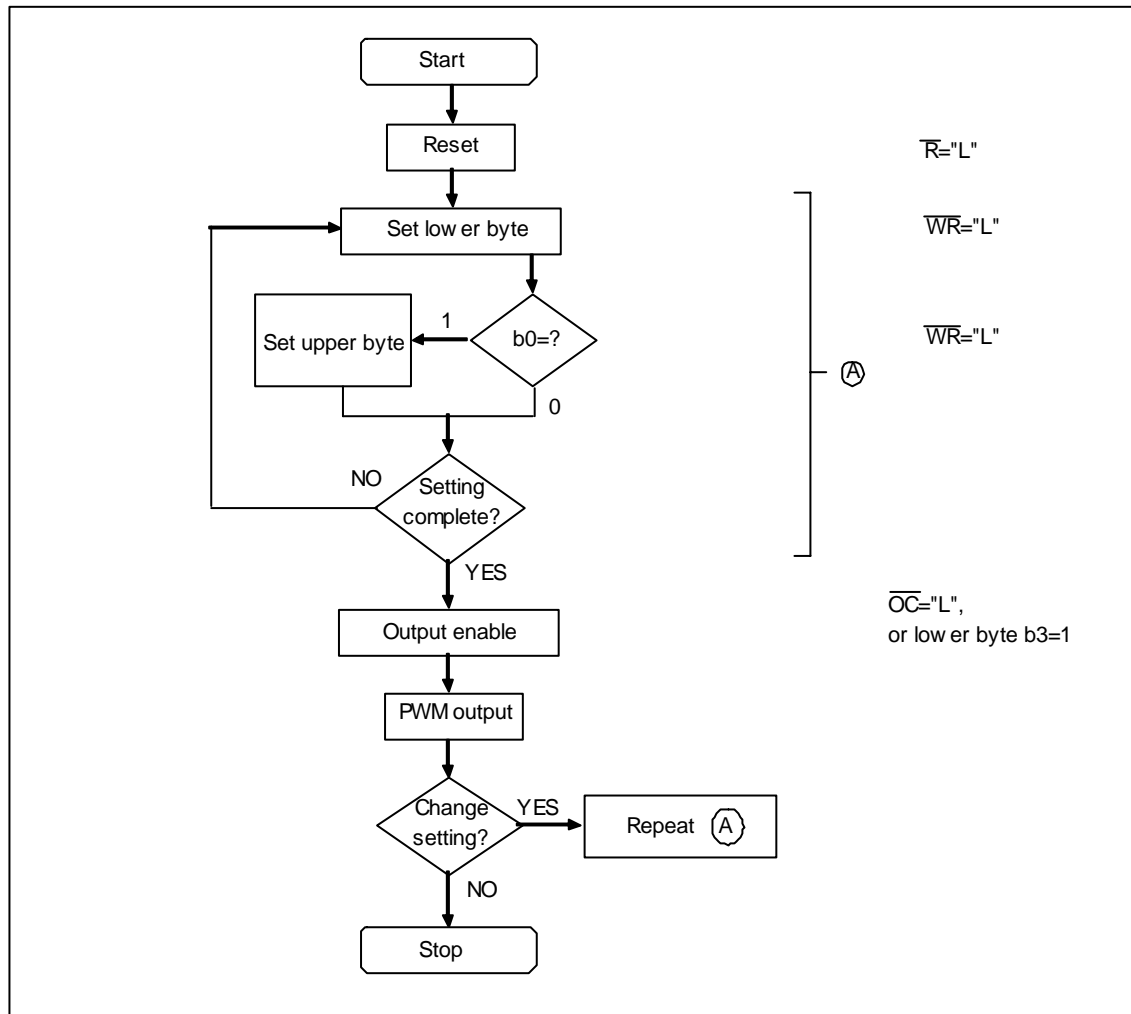


Fig.7 PWM Setting Flow Chart

ABSOLUTE MAXIMUM RATINGS (Ta= -40°C~85 °C unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
V _{cc}	Supply voltage		-0.5 ~ +7.0	V
V _I	Input voltage		-0.5 ~ V _{cc} +0.5	V
V _O	Output voltage		-0.5 ~ V _{cc} +0.5	V
I _O	Output current		±15	mA
I _{cc}	Supply/GND current	V _{cc} , GND	±40	mA
P _d	Power dissipation		150	mW
T _{stg}	Storage temperature		-65 ~ 150	°C

RECOMMENDED OPERATING CONDITIONS (Ta=-40 °C ~ 85 °C unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
V _{cc}	Supply voltage	5.0V support	4.5	5.0	5.5	V
		3.3V support	3.0	3.3	3.6	V
GND	Supply voltage			0		V
V _I	Input voltage		0		V _{cc}	V
V _O	Output voltage		0		V _{cc}	V
Topr	Operating temperature range		-40		85	°C

ELECTRICAL CHARACTERISTICS**■5.0V version support specifications** (Ta=-40 °C ~ 85 °C, V_{cc}=4.5V ~ 5.5V, unless otherwise noted)

Symbol	Parameter		Test conditions	Limits			Unit
				Min.	Typ.	Max.	
V _{IH}	“H” input voltage	X _{IN}		0.8V _{cc}			V
		Other input		0.75V _{cc}			V
V _{IL}	“L” input voltage	X _{IN}				0.2V _{cc}	V
		Other input				0.25V _{cc}	V
V _{OH}	“H” output voltage	PWM1~4	I _{OH} =-4mA	V _{cc} -0.5			V
V _{OL}	“L” output voltage	PWM1~4	I _{OL} =4mA			0.5	V
I _{IH}	“H” input current		V _I =V _{cc}			1.0	μA
I _{IL}	“L” input current		V _I =GND			-1.0	μA
I _{OZH}	Off-state “H” output current		V _O =V _{cc}			5.0	μA
I _{OZL}	Off-state “L” output current		V _O =GND			-5.0	μA
I _{cc}	Quiescent supply current		V _I =V _{cc} , GND, Output open			40	μA

■3.3V version support specifications (Ta=-40 °C ~ 85 °C, V_{cc}=3.0V ~ 3.6V, unless otherwise noted)

Symbol	Parameter		Test conditions	Limits			Unit
				Min.	Typ.	Max.	
V _{IH}	“H” input voltage	X _{IN}		0.8V _{cc}			V
		Other input		0.75V _{cc}			V
V _{IL}	“L” input voltage	X _{IN}				0.2V _{cc}	V
		Other input				0.25V _{cc}	V
V _{OH}	“H” output voltage	PWM1~4	I _{OH} =-2mA	V _{cc} -0.5			V
V _{OL}	“L” output voltage	PWM1~4	I _{OL} =2mA			0.5	V
I _{IH}	“H” input current		V _I =V _{cc}			1.0	μA
I _{IL}	“L” input current		V _I =GND			-1.0	μA
I _{OZH}	Off-state “H” output current		V _O =V _{cc}			5.0	μA
I _{OZL}	Off-state “L” output current		V _O =GND			-5.0	μA
I _{cc}	Quiescent supply current		V _I =V _{cc} , GND, Output open			40	μA

SWITCHING CHARACTERISTICS

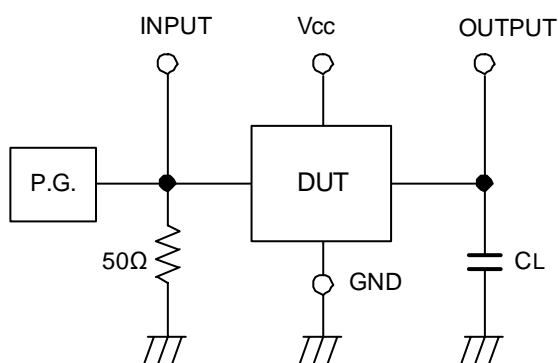
(Ta=-40°C ~ 85°C, Vcc=5.0V±0.5V or 3.3V±0.3V, unless otherwise noted)

(Ta= -40 °C to +85 °C; VCC=3.0V to 3.3V or 5.0V to 5.5V, unless otherwise noted)										
Symbol	Parameter		Test conditions	5.0V specification			3.3V specification			Unit
				Min.	Typ.	Max.	Min.	Typ.	Max.	
fmax	Maximum clock frequency	XIN	CL=50pF (Note 1)			16			12.5	MHz
tPLH	Output "L-H", "H-L" propagation time	XIN-PWM1~4				100			100	ns
tPHL						100			100	ns

TIMING REQUIREMENTS (Ta=-40°C ~ 85°C, Vcc=5.0V±0.5V or 3.3V±0.3V, unless otherwise noted)

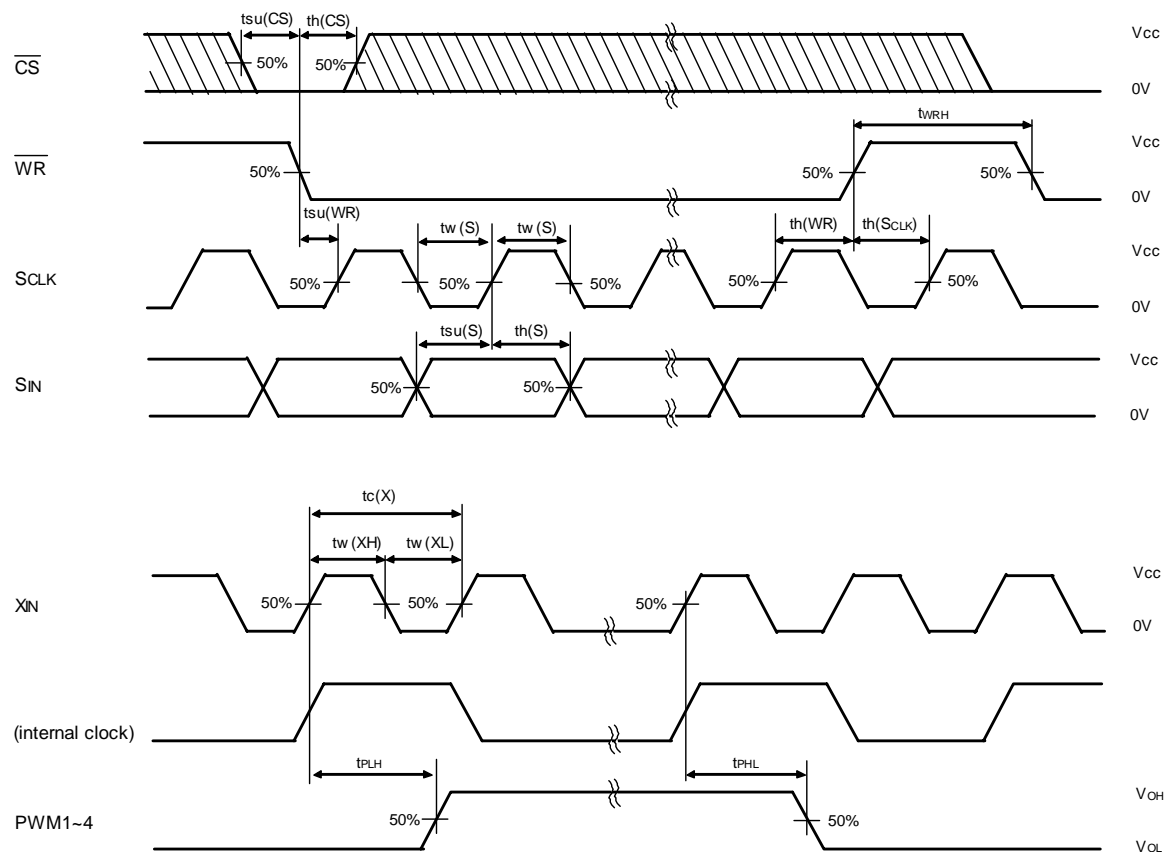
Symbol	Parameter	Test conditions	5.0V specification			3.3V specification			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
tc(X)	XIN cycle time		62.5			80			ns
tw(XH)	XIN "H" pulse width		32.5			40			ns
tw(XL)	XIN "L" pulse width		30			40			ns
tw(S)	SCLK pulse width		30			40			ns
twRH	WR "H" hold time		6tc(x)			6tc(x)			ns
tsu(CS)	CS "L" setup time before WR↓		30			40			ns
tsu(WR)	WR "L" setup time before SCLK↑		30			40			ns
tsu(S)	SIN setup time before SCLK↑		50			60			ns
th(CS)	CS "L" hold time after WR↓		30			40			ns
th(WR)	WR "L" hold time after SCLK↑		10			20			ns
th(S)	SIN hold time after SCLK↑		10			20			ns
th(SCLK)	SCLK hold time after WR↑		30			40			ns
tr	Input rise time				25			25	ns
tf	Input fall time				25			25	ns

Note 1. Test Circuit



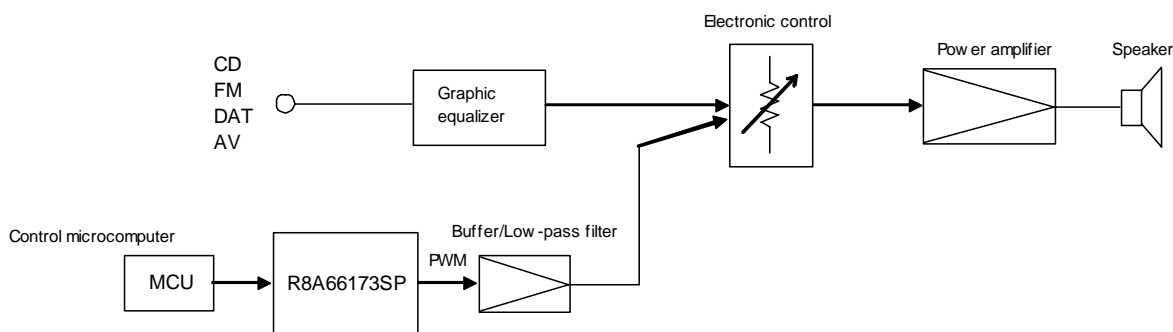
- (1) The pulse generator (PG) has the following characteristics. : tr=3ns, tf=3ns
- (2) The capacitance CL includes stray wiring capacitance and the probe input capacitance.

TIMING CHARTS



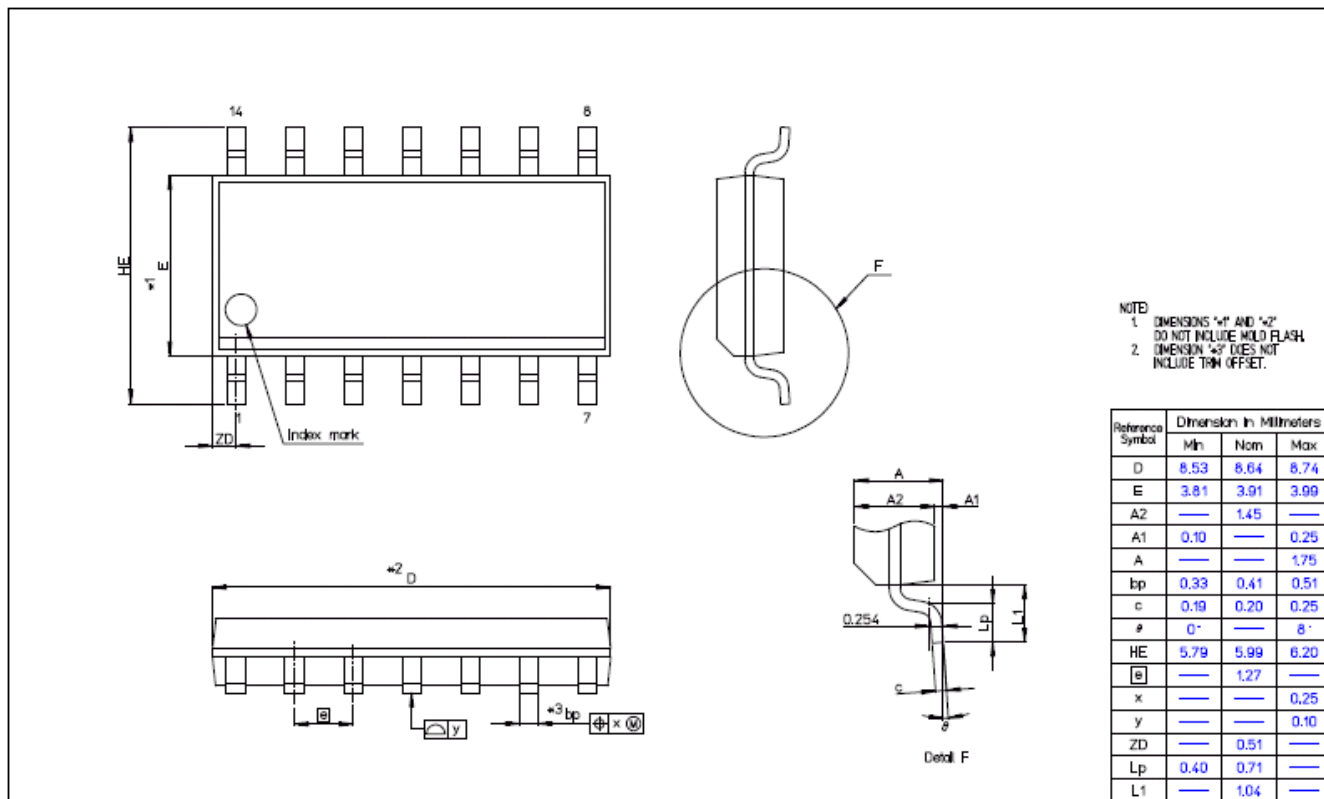
Note 2. (1) Shaded portions indicate that switching is possible during those periods.
 (2) PWM outputs 1 to 4 change synchronously with internal clock signals Φ .
 The frequency of these signals is the 1/2 divider of the frequency input from XIN.

APPLICATION EXAMPLE (Combination with electronic control for amplifier system)



PACKAGE OUTLINE

Package	RENESAS Code	Previous Code
14pin SOP	PRSP0014DG-A	14P2X-B



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